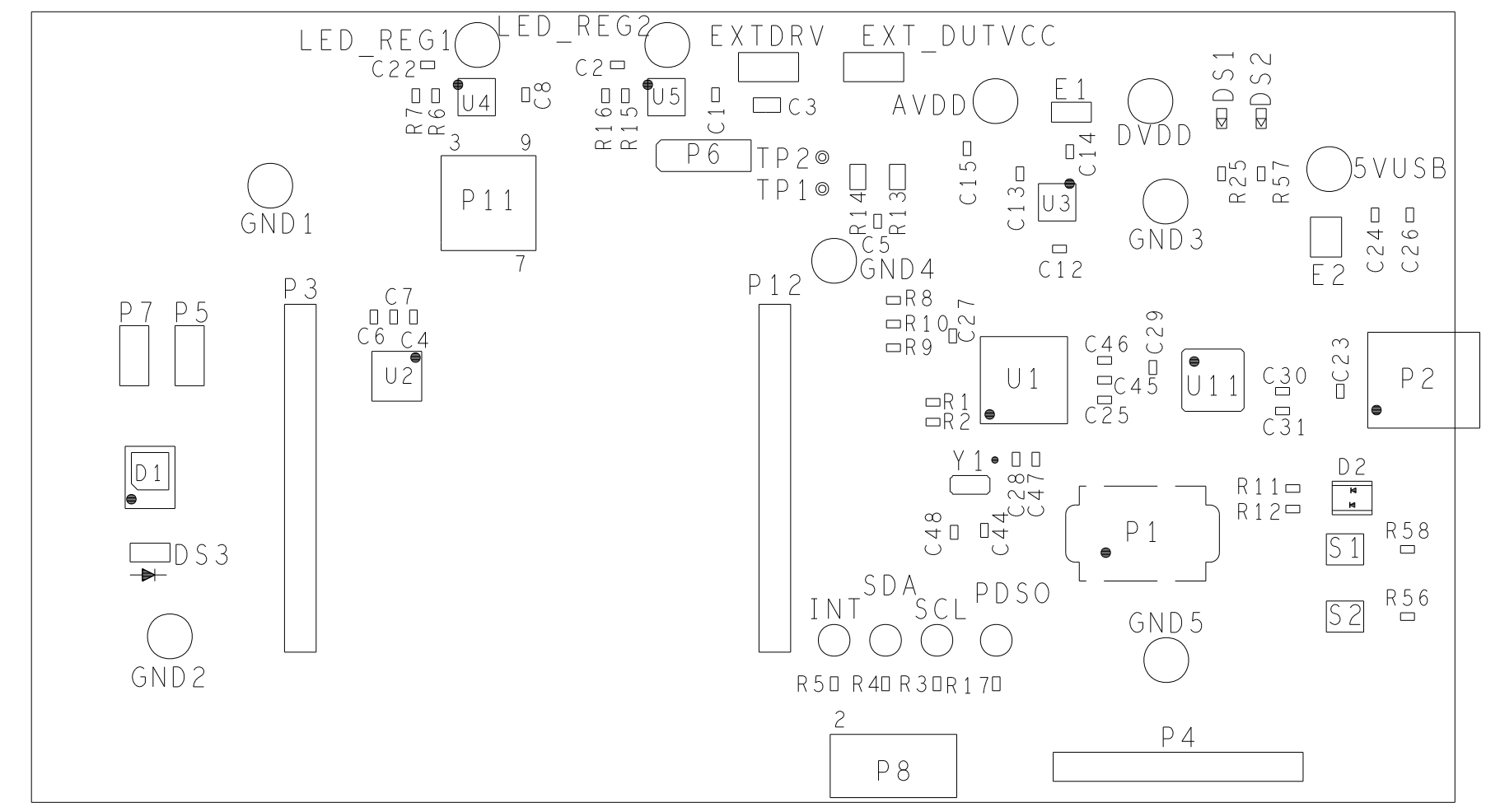
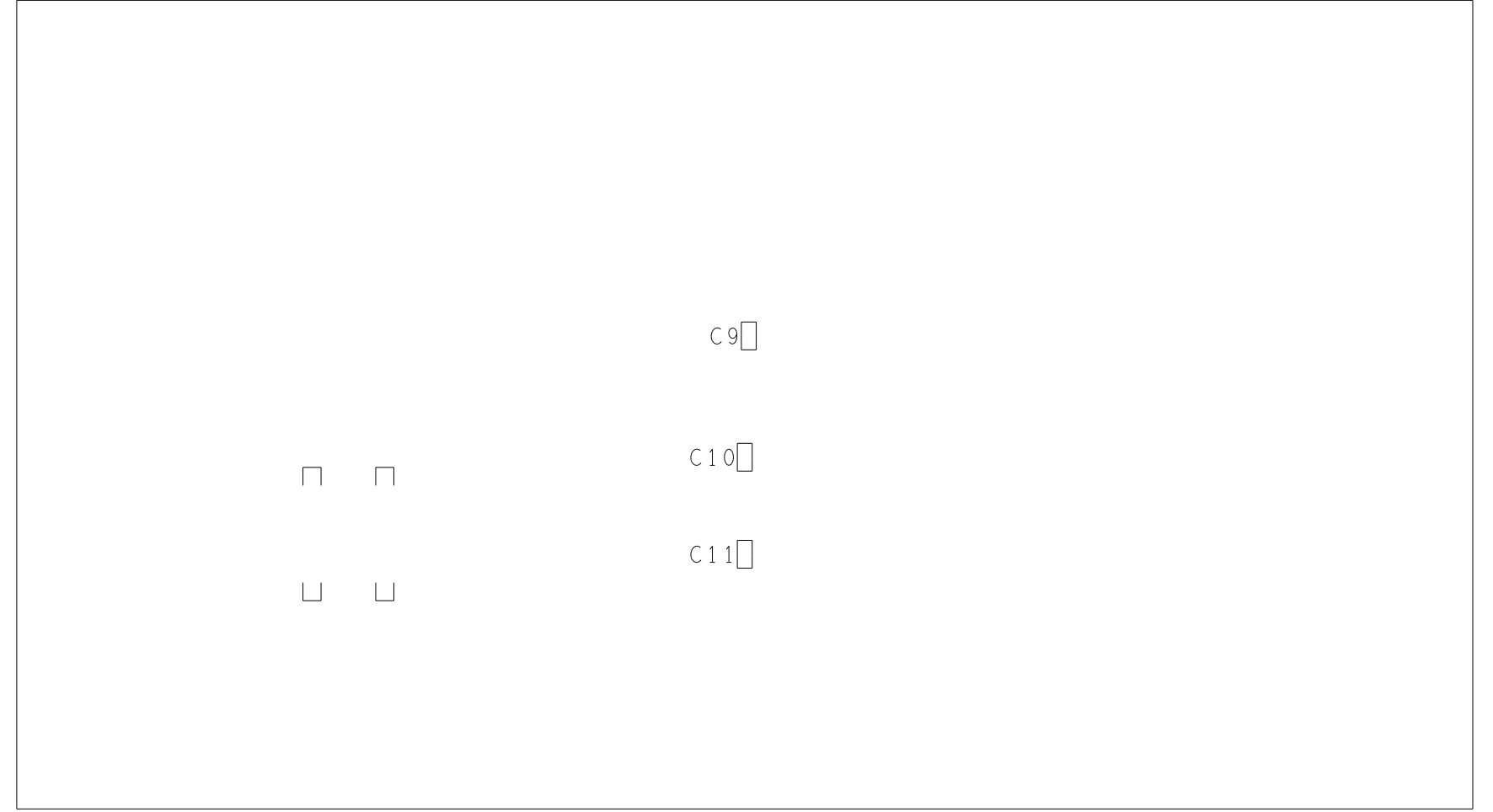


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	18SEP15	K.B.

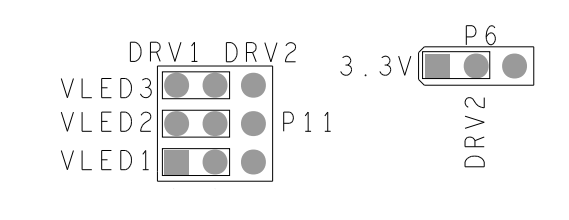


PRIMARY SIDE




SECONDARY SIDE

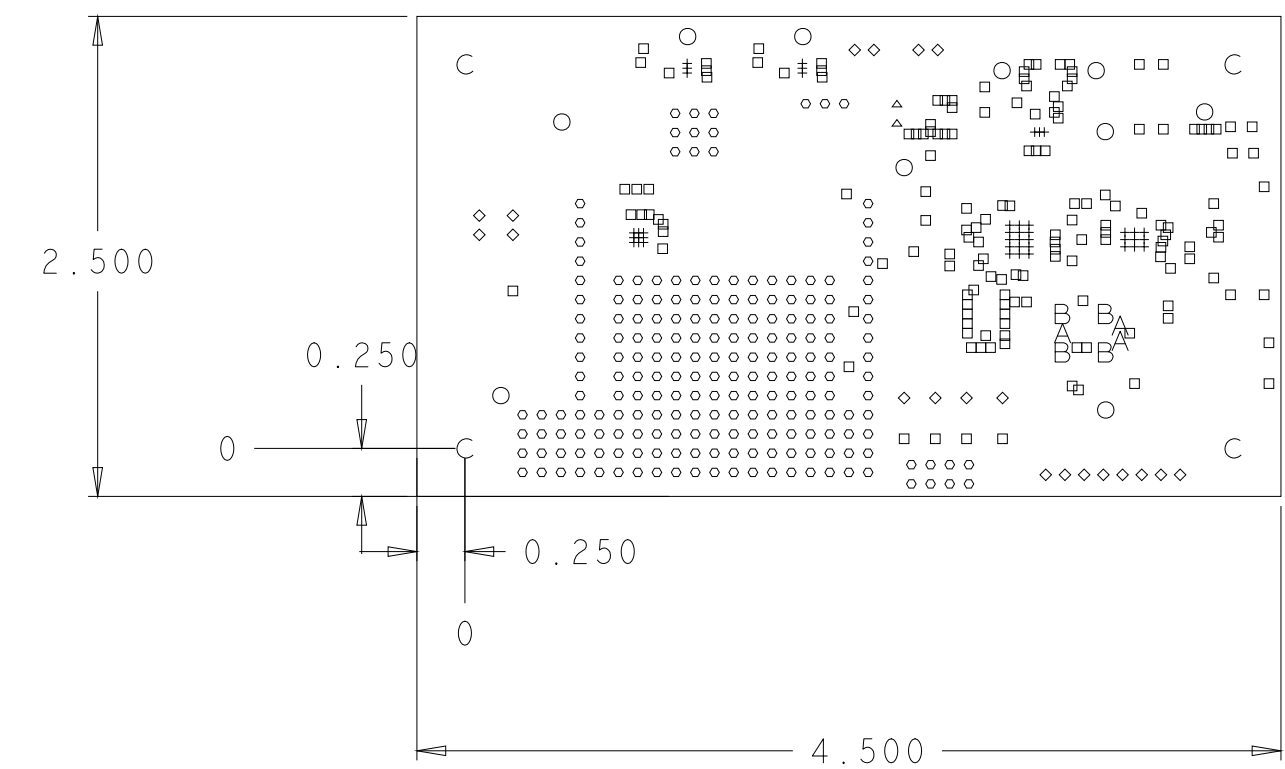
- ASSEMBLY NOTES:
1. DEFAULT SHUNT PLACEMENT BELOW
CONNECT P11 PINS 1 TO 4, 2 TO 5 AND 3 TO 6
CONNECT P6 PINS 1 TO 2
 2. CONNECT P5 AND P7 SHUNTS ACROSS PINS 1 AND 2



PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES		APPROVAL	DATE	 ASC DIVISION 804 WOBURN STREET WILMINGTON, MA 01887	
TOLERANCES		TEMPLATE ENGINEER R. MARION	ddMMyy	TITLE ASSEMBLY ADPD103 EVALUATION BD Z	
DECIMALS FRACTIONS ANGLES		HARDWARE SERVICES	ddMMyy		
.XX -.010		HARDWARE SYSTEMS	ddMMyy		
.XXX -.005		TEST ENGINEER	ddMMyy		
.XXXX -.0050		COMPONENT ENGINEER	ddMMyy	SIZE FSCM NO DRAWING NUMBER REV D 24355 01-041319 A	
MATERIAL		TEST PROCESS	ddMMyy		
FINISH		HARDWARE RELEASE	ddMMyy		
DESIGNER V. GUTBIER		DATE	25AUG15		
P10 ENGINEER K. BUCKLEY		DATE	18SEP15	SCALE 1/1 SHEET 1 OF 1	
CHECKER J. MORIN		DATE	10SEP15		
DO NOT SCALE DWG					

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	18SEP15	K.B.



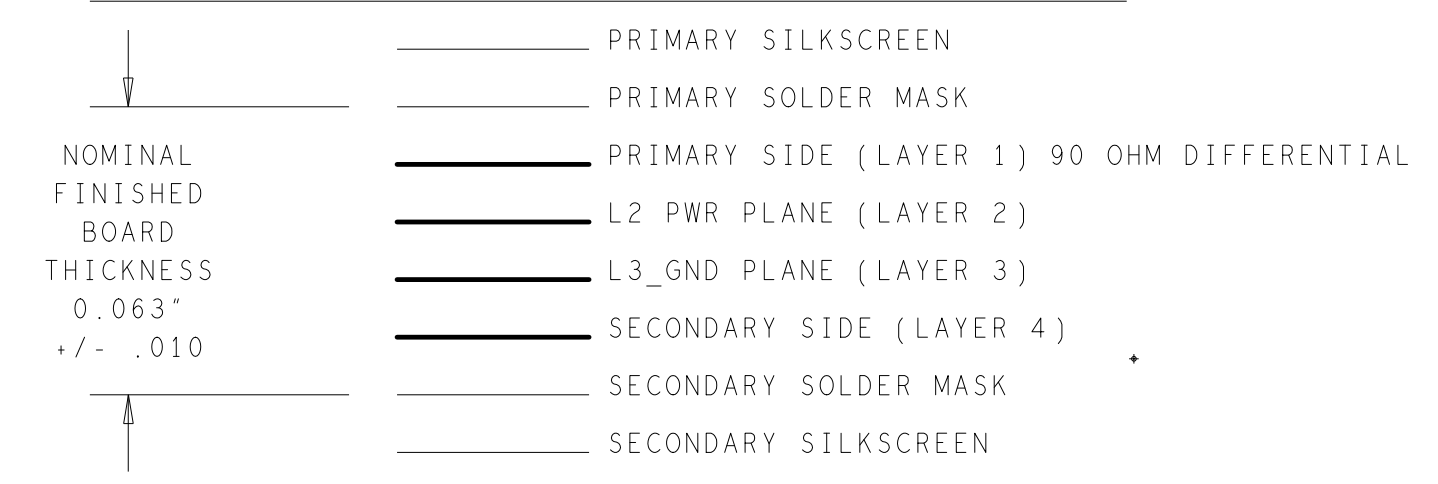
SPECIFICATIONS:

- MATERIALS;** ALL LAMINATES AND BONDING MATERIALS SHOULD BE SELECTED FROM IPC-4101 OR IPC-4103, MINIMUM Tg>170degC, Td>300degC, U.L. RATING OF 94 V-0
- MATERIAL FAMILY;** ISOLA 370HR
- CLADDING;** EXTERNAL LAYERS .5 OZ. COPPER, OVERPLATE TO 1.5 OZ. INTERNAL PLANE LAYERS 1 OZ. COPPER.
- SOLDER MASK;** SHALL BE LIQUID PHOTOIMAGEABLE (LPI) APPLIED ON BOTH SIDES OVER BARE COPPER OR GOLD AND SHALL MEET IPC-SM-840 (LATEST REV.) CLASS 3, COLOR BLUE.
- SILK SCREEN;** SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK, COLOR: WHITE SYNTHETIC INKJET PRINTING ALLOWED FOR DENSE BOARDS, COLOR: WHITE
- SURFACE FINISH;** ENIG, IMERSION GOLD PLATING, 2-8 MICRO INCHES GOLD OVER ELECTROLESS NICKEL PLATING 100 MICRO INCHES MINIMUM PER QQ-N-290, CLASS I
- INTENTIONAL SHORTS;** IF SUPPLIED DATA INCLUDES A FILE "READ_ME.2", THEN INTENTIONAL NET SHORTS EXIST. CUSTOMER REVIEW AND APPROVAL IS REQUIRED IF SUPPLIED DATA REPORTS ANY CONDITION THAT DOES NOT MATCH "READ_ME.2" FILE PROVIDED.
- TEST REQUIREMENTS;** 100% NETLIST ELECTRICAL VERIFICATION USING CUSTOMER SUPPLIED IPC-D-356 NETLIST FOR OPENS AND SHORTS WHEN "GERBER DATA" IS PROVIDED. THIS VERIFICATION ALSO REQUIRED FOR "ODB++" DATA PER EMBEDDED NETLIST.

REQUIREMENTS:

- REFER TO IPC-6010 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
- ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00115. (LATEST REVISION.)
- MODIFICATIONS TO THE ARTWORK ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
- HOLE PATTERN TOLERANCES FOR UNDIMENSIONED HOLES SHALL BE A DIAMETER OF 0.005 INCHES FROM THEIR TRUE POSITION.
- PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN 0.001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY CROSS SECTION.
- HOLE DIAMETERS APPLY AFTER PLATING.
- FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
- MINIMUM DESIGN LINE WIDTH IS .008 INCH.
- MINIMUM DESIGN SPACING IS .006 INCH.
- NON-FUNCTIONAL PAD REMOVAL FROM INNER SIGNAL LAYERS MAY BE PERFORMED AFTER CUSTOMER APPROVAL.
- IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNULAR RING REQUIREMENT, MFR. MAY REQUEST APPROVAL TO TEAR DROP PADS TO MAINTAIN ANNULAR RING. (AT PAD TO TRACE INTERSECTION ONLY AND ELECTRICAL INTEGRITY MUST BE MAINTAINED.)
- THIEVING MAY BE ADDED TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN ONLY AFTER REVIEW AND APPROVAL FROM THE CUSTOMER:
 - A. THIEVING TO CARD EDGE, FIDUCIALS, NON-PLATED THROUGH HOLES, ALL OTHER FEATURES TO BE 0.200 INCH MINIMUM.
 - B. THERE SHALL BE NO THIEVING IN ANY AREAS FREE OF SOLDER MASK OR INTERNAL COPPER PLANES.
- MFR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED;
 - A. U.L. CODE-FLAMMABILITY RATING
 - B. DATE CODE (STAMP)
 - C. LOT NUMBER
 - D. MFR LOGO
 - E. SUCCESSFUL ELECTRICAL TEST.
- REPAIRS PER IPC-7711/21 (LATEST REV.) ARE ALLOWED.
- THRU VIAS FILLED WITH NON-CONDUCTIVE EPOXY AND PLATED OVER. COPLANAR ON BOTH SIDES WITHIN .001 INCH PRIOR TO FINAL PLATING.
- BOARDS TO BE PANELIZED BEST FIT.

4 LAYER STACKUP



CHARACTERISTIC IMPEDANCE = 90 OHMS DIFF +/-10%
 ARTWORK LINE WIDTH FOR IMPEDANCE CONTROLLED LINES = 0.010" TRACE/0.009" GAP FOR LAYER 1.

HOLE TOLERANCE

UNLESS SPECIFIED
 PLATED: +/- 3
 NON PLATED: +/- 3

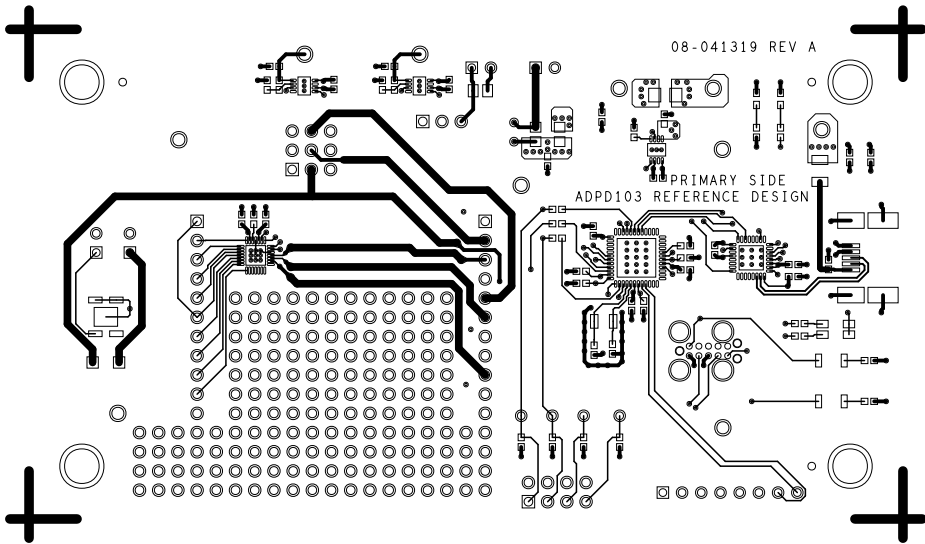
FINISHED HOLES IN MILS				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
*	10.0	PLATED	42	MAX DIA
□	12.0	PLATED	157	MAX DIA
△	25.0	PLATED	2	
○	40.0	PLATED	20	
○	45.0	PLATED	202	
○	63.0	PLATED	10	
A	39.0	NON-PLATED	3	
B	94.0	NON-PLATED	4	
C	180.0	NON-PLATED	4	

SEE NOTE 15

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES		APPROVAL	DATE	ANALOG DEVICES		ASC DIVISION 804 WOBURN STREET WILMINGTON, MA 01887	
TOLERANCES	FRACTIONS	DESIGNER R. MARION	ddMMyy	TITLE FABRICATION ADPD103 EVALUATION BD Z			
DECIMALS	ANGLES	HARDWARE SERVICES	ddMMyy				
.XX -.010	..1/32	HARDWARE SYSTEMS	ddMMyy				
.XXX -.005	..2	TEST ENGINEER	ddMMyy				
.XXXX -.0050		COMPONENT ENGINEER	ddMMyy	SIZE	FSCM NO	DRAWING NUMBER	REV
MATERIAL	TEST PROCESS	V. GUTBIER	ddMMyy	D	24355	09-041319	A
	HARDWARE RELEASE	K. BUCKLEY	ddMMyy	SCALE	1/1	SHEET	1 OF 1
FINISH		J. MORIN	ddMMyy				

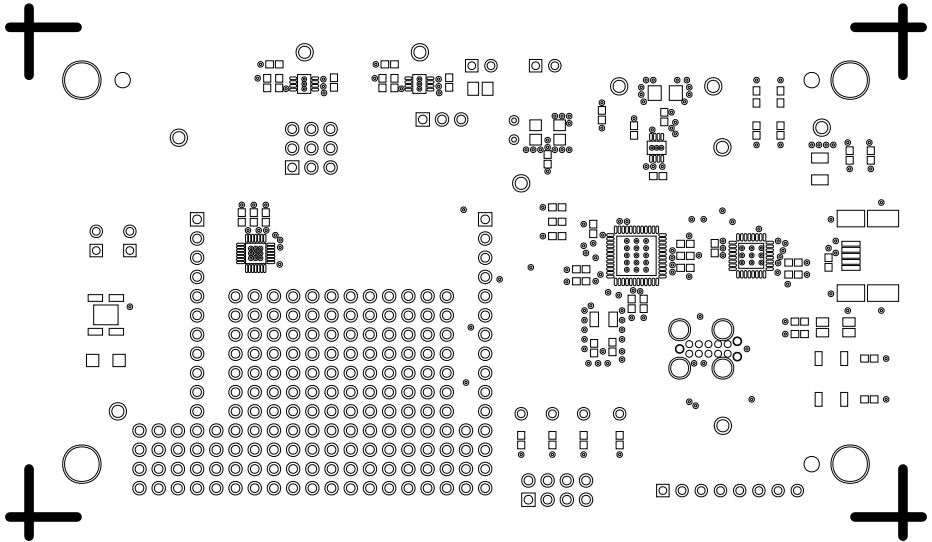
L1 PRIMARY
08-041319-01
REV A



SOLDERMASK PRIMARY

08-041319-04

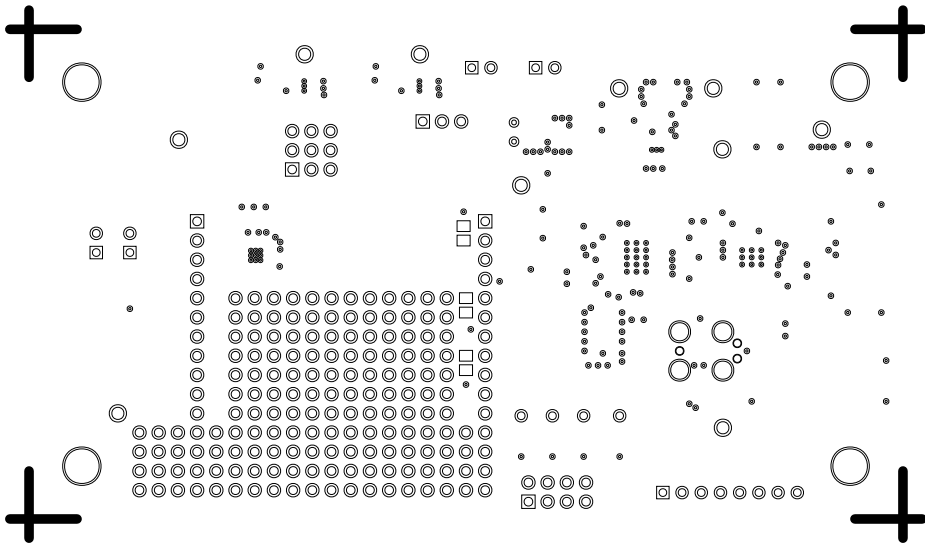
REV A



SOLDERMASK SECONDARY

08-041319-06

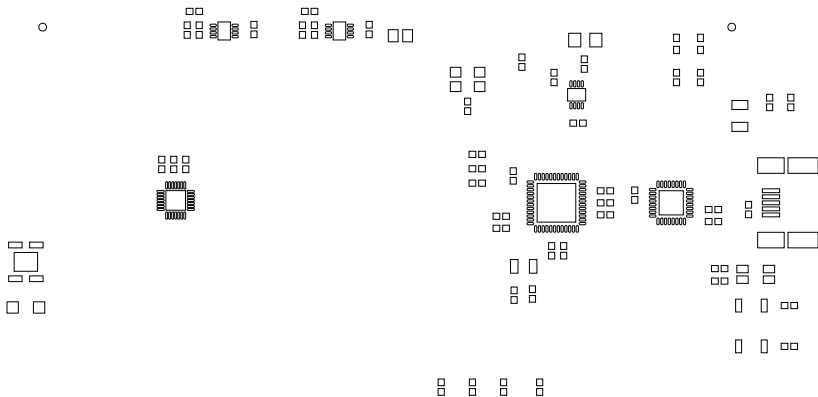
REV A



PASTEMASK PRIMARY

08-041319-07

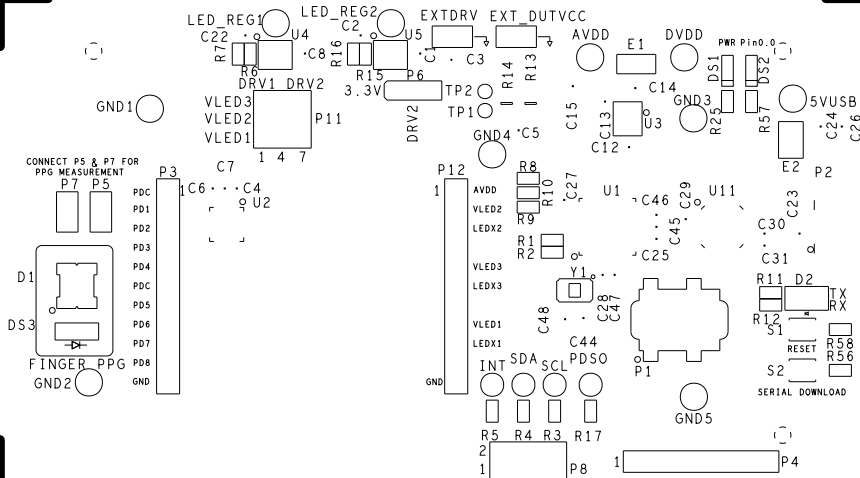
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SILKSCREEN PRIMARY

08-041319-03

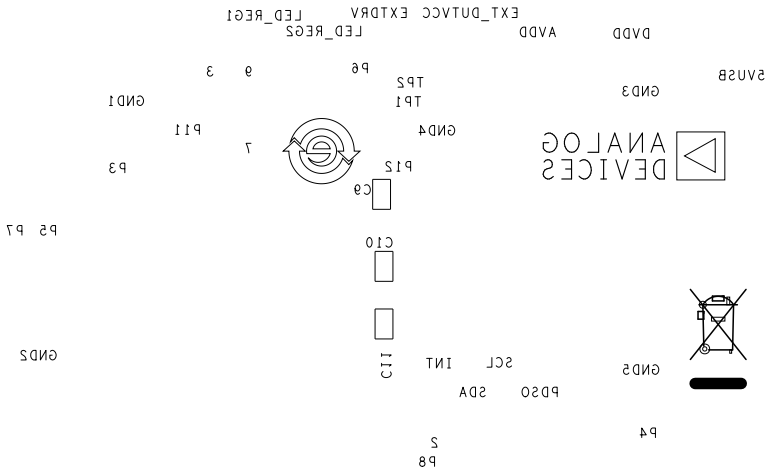
REV A



SILKSCREEN SECONDARY

08-041319-05

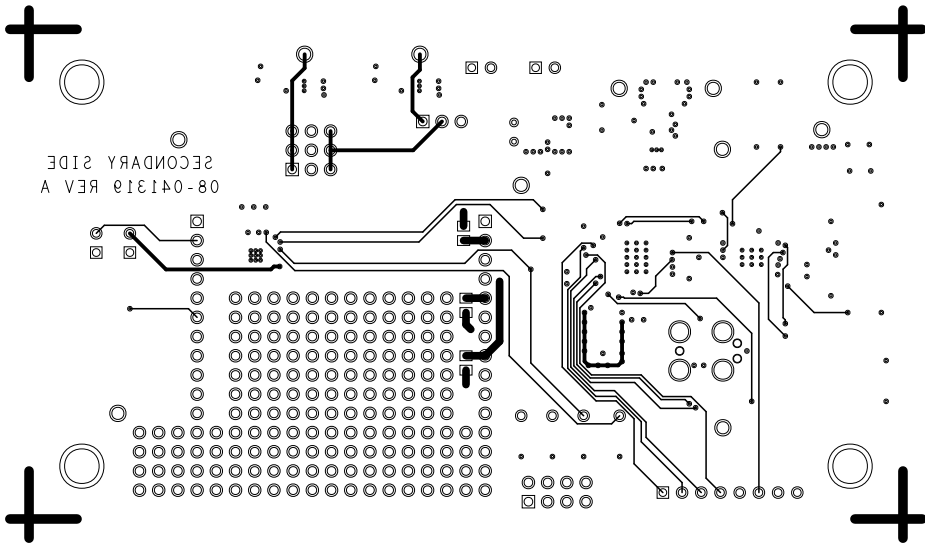
REV A



L4 SECONDARY

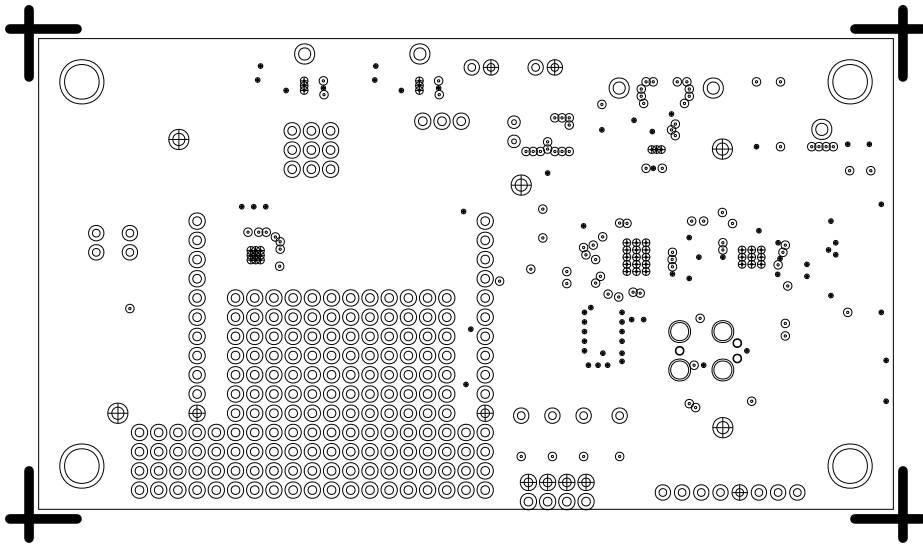
08-041319-02

REV A



SECONDARY SIDE
08-041319 REV A

L2_GND
08-041319-07
REV A



L3_PWR

08-041319-08

REV A

